

1 Characteristics

Table 1. In compliance with the following standards

Standard	Peak surge voltage (V)	Waveform voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μ s 10/1000 μ s	500 100	2/10 μ s 10/1000 μ s	0 0
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	0
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0
ITU-T-K20/K21	6000 1500	10/700 μ s	150 37.5	5/310 μ s	0 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
IEC61000-4-5	4000 4000	10/700 μ s 1.2/50 μ s	100 100	5/310 μ s 8/20 μ s	0 0
TIA/EIA IS-968, lightning surge type A	1500 800	10/160 μ s 10/560 μ s	200 100	10/160 μ s 10/560 μ s	0 0
TIA/EIA IS-968, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0

Table 2. Absolute ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter		Value	Unit
I_{PP}	Repetitive peak pulse current (see Figure 2)	10/1000 μs	100	A
		8/20 μs	400	
		10/560 μs	140	
		5/310 μs	150	
		10/160 μs	200	
		1/20 μs	400	
		2/10 μs	500	
I_{FS}	Fail-safe mode: maximum current ⁽¹⁾	8/20 μs	5	kA
I_{TSM}	Non repetitive surge peak on-state current (sinusoidal)	$t = 0.2\text{ s}$	24	A
		$t = 1\text{ s}$	15	
		$t = 2\text{ s}$	12	
		$t = 15\text{ mn}$	4	
I^2t	I^2t value for fusing	$t = 16.6\text{ ms}$	20	A^2s
		$t = 20\text{ ms}$	21	
T_{stg}	Storage temperature range		-55 to 150	$^{\circ}\text{C}$
T_j	Operating junction temperature range		-40 to 150	
T_L	Maximum lead temperature for soldering during 10 s.		260	$^{\circ}\text{C}$

1. In fail safe mode, the device acts as a short circuit.

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient (with recommended footprint)	100	$^{\circ}\text{C/W}$
$R_{th(j-l)}$	Junction to leads	20	$^{\circ}\text{C/W}$

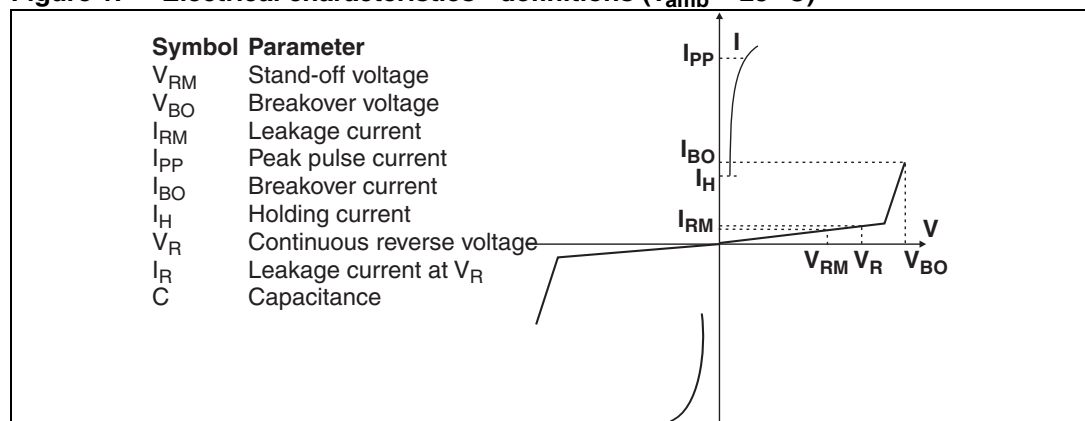
Figure 1. Electrical characteristics - definitions ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Table 4. Electrical characteristics - values ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Order code	$I_{RM} @ V_{RM}$		$I_R @ V_R$		Dynamic $V_{BO}^{(1)}$	Static $V_{BO} @ I_{BO}^{(2)}$		$I_H^{(3)}$	$C^{(4)}$	$C^{(5)}$
	max.		max.		max.	max.	max.	min.	typ.	typ.
	μA	V	μA	V	V	V	mA	mA	pF	pF
SMP100LC-8	2	6	5	8	25	15	800	50 (typ.)	NA	75
SMP100LC-25		22		25	40	35		150	NA	65
SMP100LC-35		32		35	55	55			NA	55
SMP100LC-65		55		65	85	85			45	90
SMP100LC-90		81		90	120	125			40	80
SMP100LC-120		108		120	155	150			35	75
SMP100LC-140		126		140	180	175			30	65
SMP100LC-160		144		160	205	200			30	65
SMP100LC-200		180		200	255	250			30	60
SMP100LC-230		207		230	295	285			30	60
SMP100LC-270		243		270	345	335			30	60
SMP100LC-320		290		320	400	390			25	50
SMP100LC-360		325		360	460	450			25	50
SMP100LC-400		360		400	540	530			20	45

1. See [Figure 16: Test circuit 1 for Dynamic \$I_{BO}\$ and \$V_{BO}\$ parameters](#)
2. See [Figure 17: Test circuit 2 for \$I_{BO}\$ and \$V_{BO}\$ parameters](#)
3. See [Figure 18: Test circuit 3 for dynamic \$I_H\$ parameter](#)
4. $V_R = 50\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$
5. $V_R = 2\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$

Figure 2. Pulse waveform

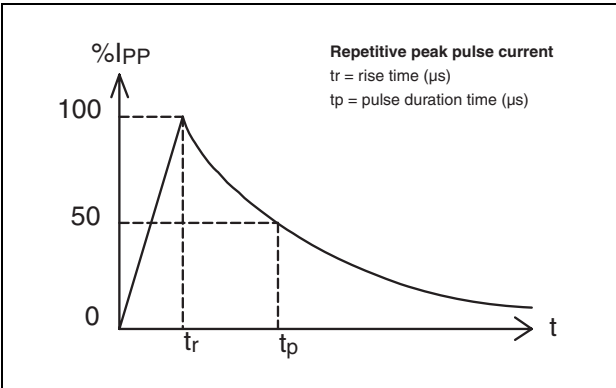


Figure 3. Non repetitive surge peak on-state current versus overload duration

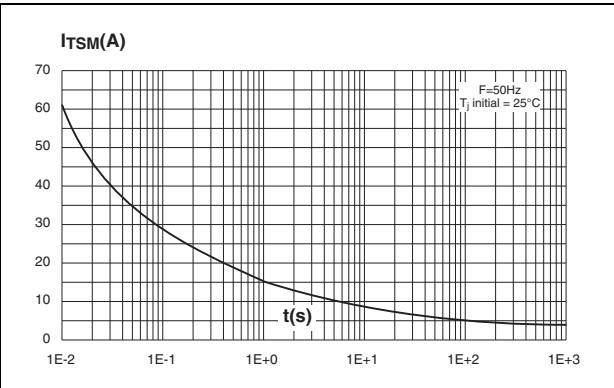


Figure 4. On-state voltage versus on-state current (typical values)

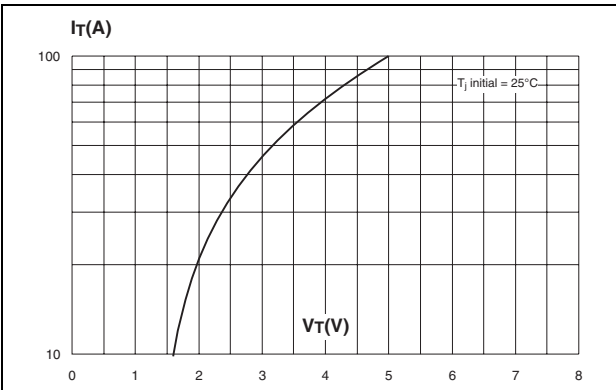


Figure 5. Relative variation of holding current versus junction temperature

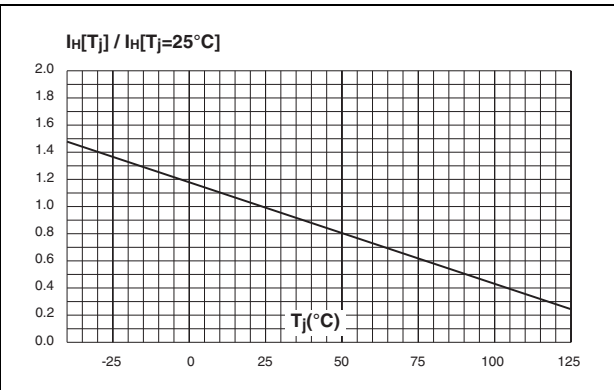


Figure 6. Relative variation of breakover voltage versus junction temperature

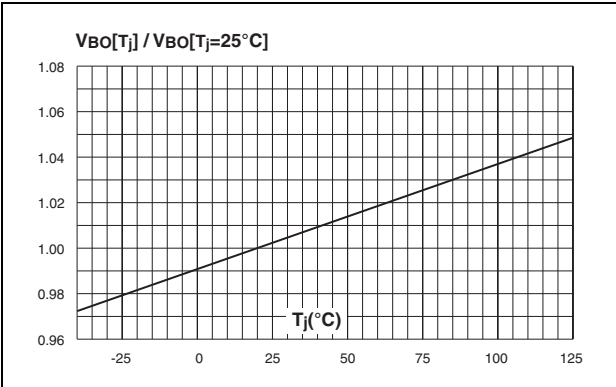


Figure 7. Relative variation of leakage current versus junction temperature (typical values)

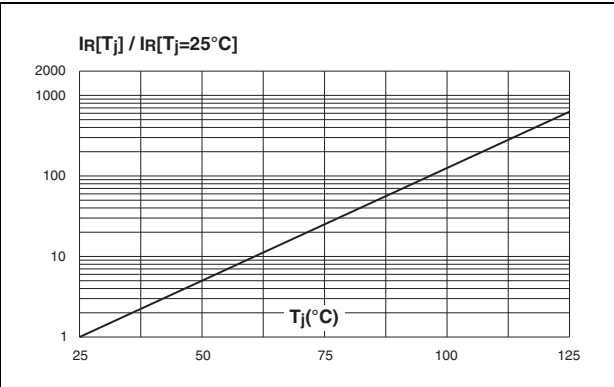


Figure 8. Variation of thermal impedance junction to ambient versus pulse duration

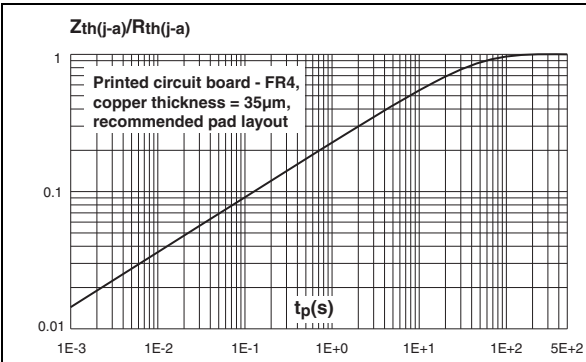
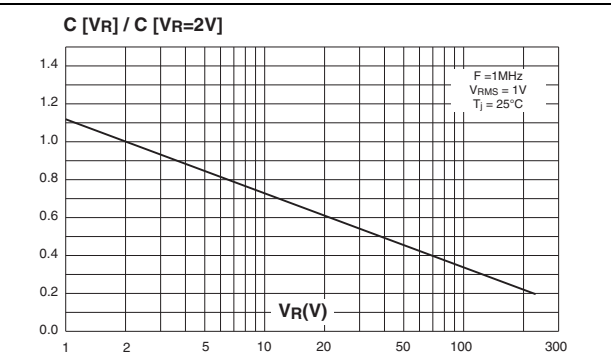


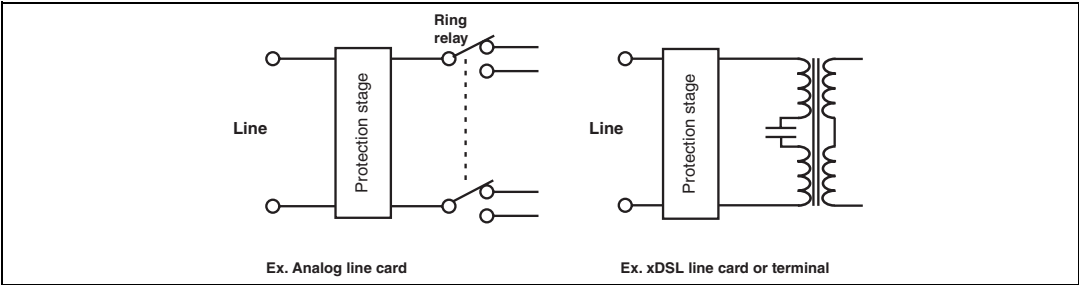
Figure 9. Relative variation of junction capacitance versus reverse voltage applied (typical values)



2 Application information

In wire line applications, analog or digital, both central office and subscriber sides have to be protected. This function is assumed by a combined series / parallel protection stage.

Figure 10. Examples of protection stages for line cards



In such a stage, parallel function is assumed by one or several Trisil, and is used to protect against short duration surge (lightning). During this kind of surges the Trisil limits the voltage across the device to be protected at its break over value and then fires. The fuse assumes the series function, and is used to protect the module against long duration or very high current mains disturbances (50/60Hz). It acts by safe circuit opening. Lightning surge and mains disturbance surges are defined by standards like GR1089, TIA/EIA IS-968, ITU-T K20.

Figure 11. Typical circuits

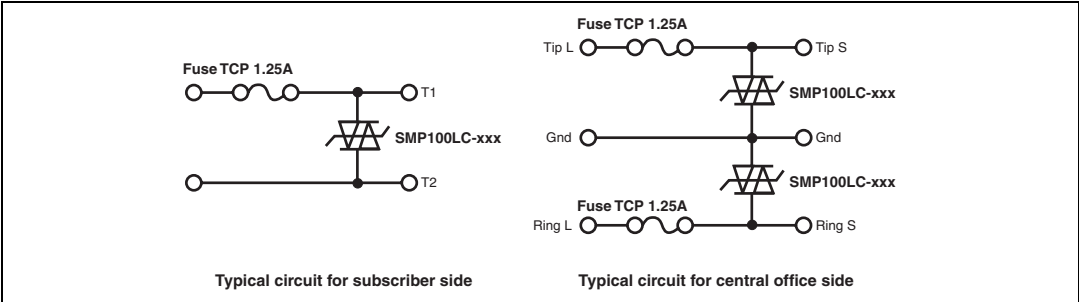
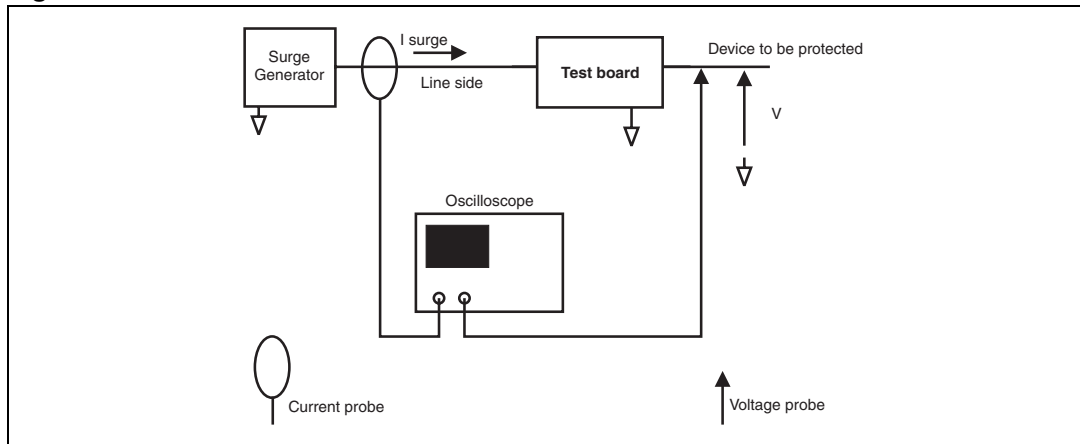
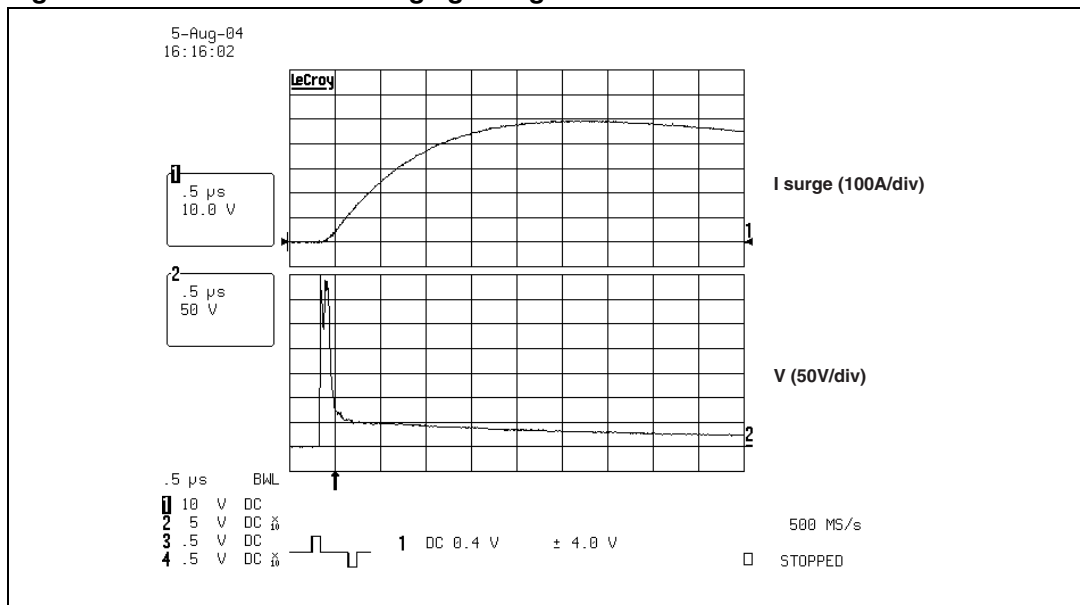


Figure 12. Test method of the board with fuse and Trisil

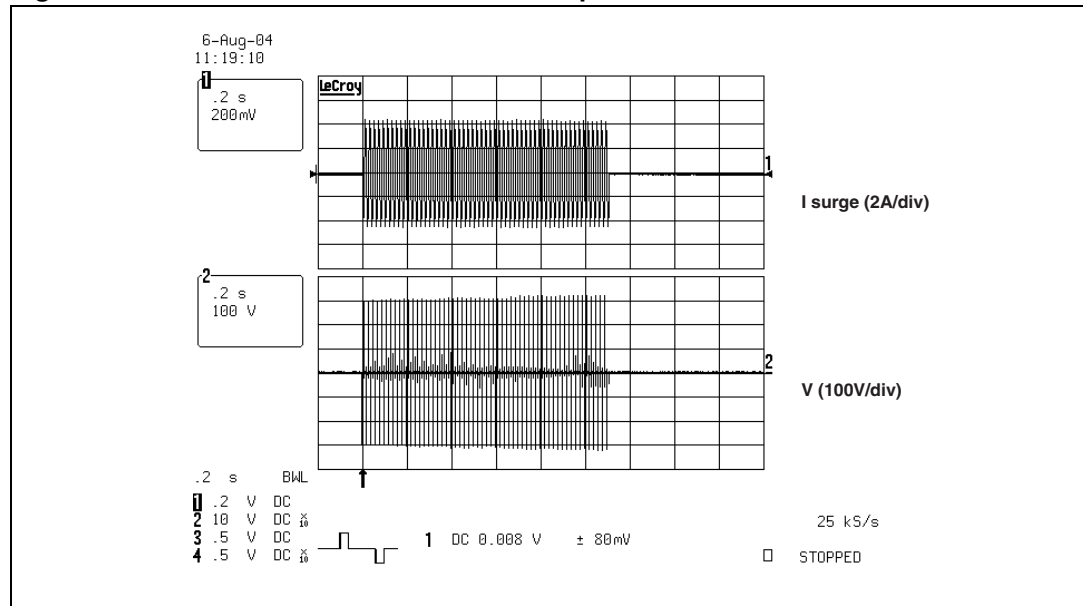
These topologies, using SMP100LC from ST and TCP1.25A from Cooper Bussmann, have been functionally validated with a Trisil glued on the PCB. Following example was performed with SMP100LC-270 Trisil. For more information, see Application Note AN2064.

Figure 13. Trisil turns on during lightning strike**Test conditions:**

2/10 μ s + and - 2.5 and 5 kV, 500 A (10 pulses of each polarity), $T_{amb} = 25^\circ\text{C}$

Test result:

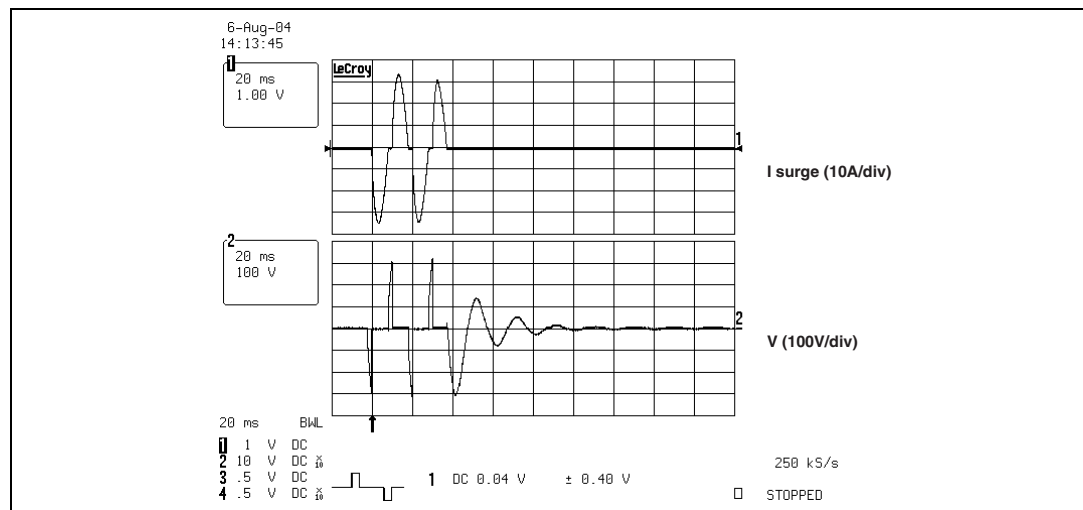
Fuse and Trisil OK after test in accordance with GR1089 requirements.

Figure 14. Trisil action while fuse remains operational**Test conditions:**

600 V, 3 A, 1.1 s (first level), $T_{amb} = 25\text{ }^{\circ}\text{C}$

Test result:

Fuse and Trisil OK after test in accordance with GR1089 requirements.

Figure 15. High current AC power test: the fuse acts like a switch by opening the circuit**Test conditions:**

277 V, 25 A (second level), $T_{amb} = 25\text{ }^{\circ}\text{C}$

Test result:

Fuse safely opened and Trisil OK after test in accordance with GR1089 requirements.

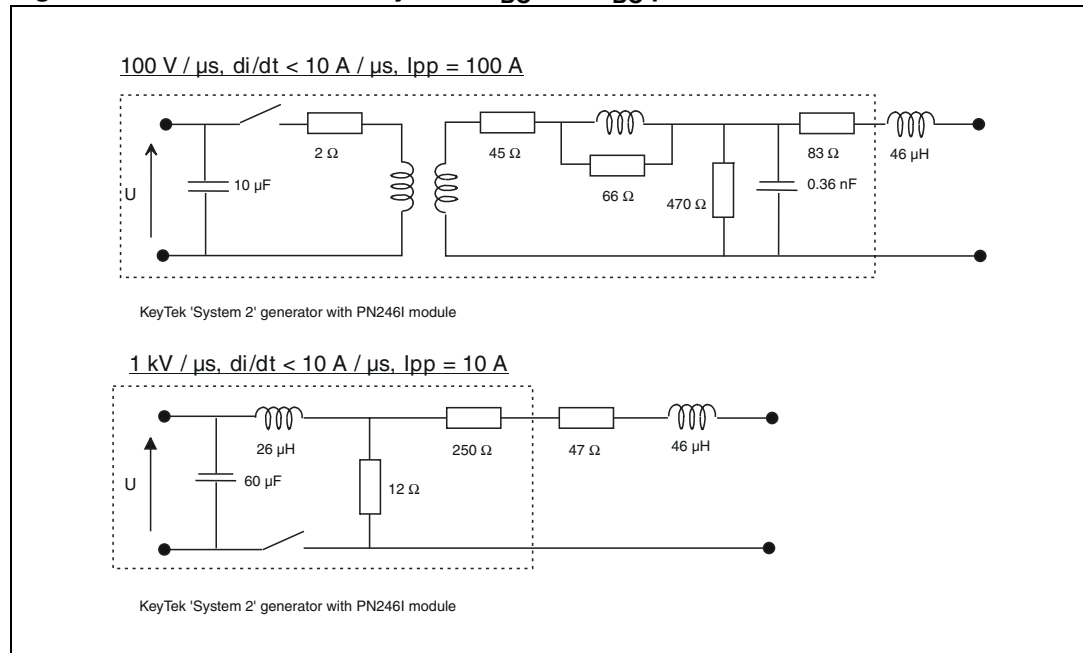
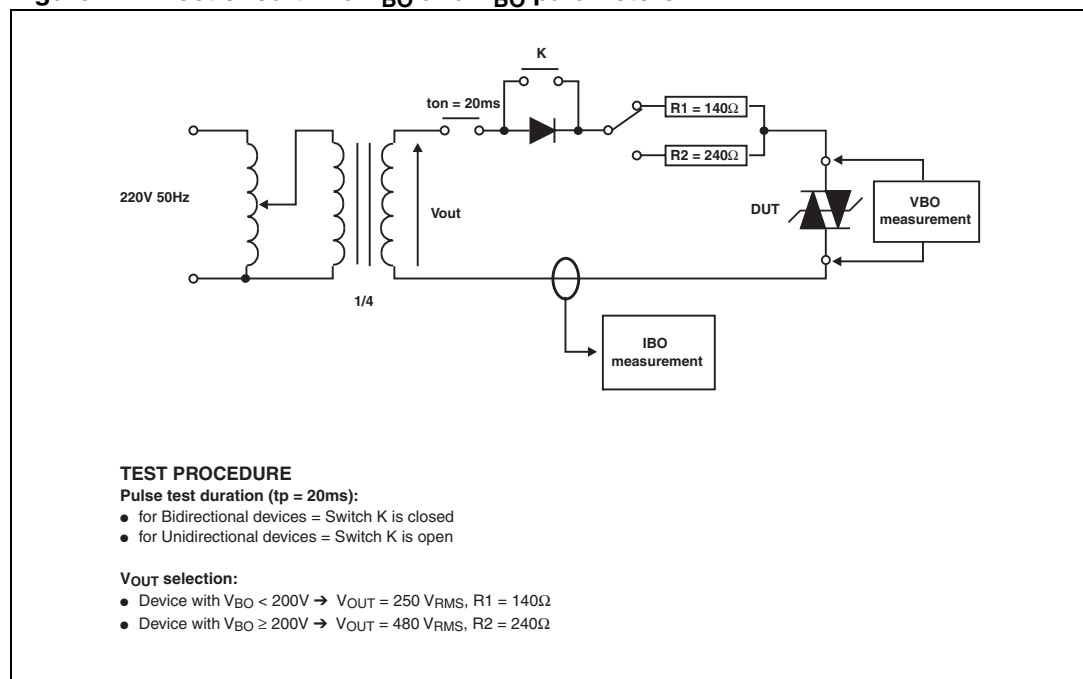
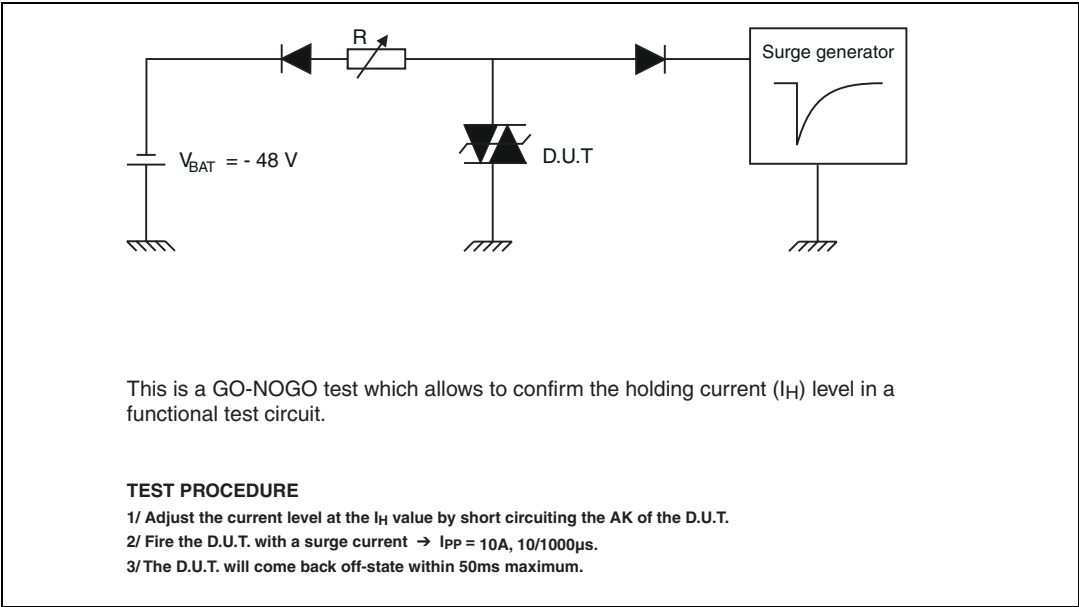
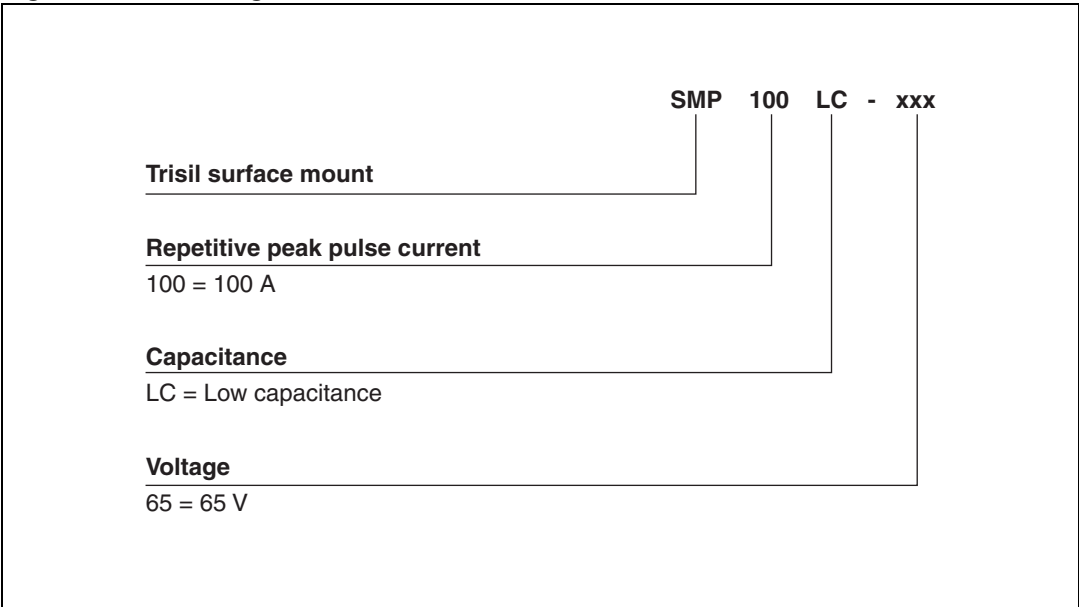
Figure 16. Test circuit 1 for Dynamic I_{BO} and V_{BO} parametersFigure 17. Test circuit 2 for I_{BO} and V_{BO} parameters

Figure 18. Test circuit 3 for dynamic I_H parameter



3 Ordering information scheme

Figure 19. Ordering information scheme



4 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. SMB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

Figure 20. Footprint dimensions in mm (inches)

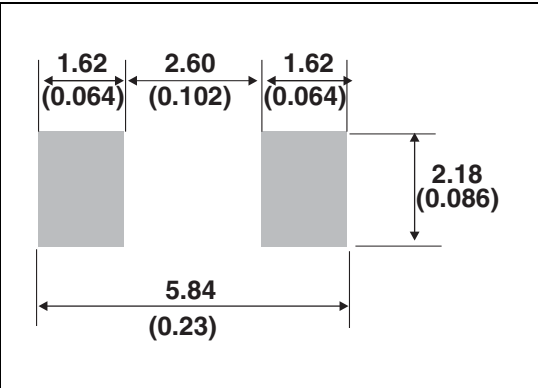
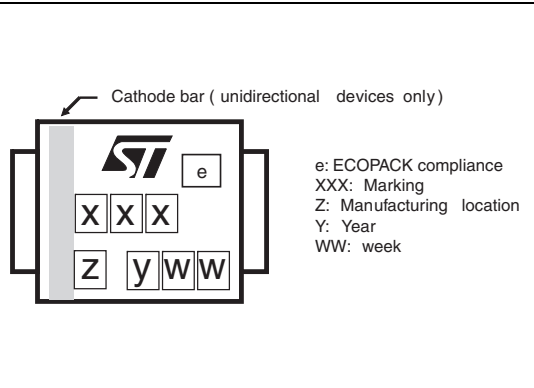


Figure 21. Marking layout⁽¹⁾



1. Marking layout can vary according to assembly location.

5 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
SMP100LC-8	PL8	SMB	98 mg	2500	Tape and reel
SMP100LC-25	L25				
SMP100LC-35	L35				
SMP100LC-65	L06				
SMP100LC-90	L09				
SMP100LC-120	L12				
SMP100LC-140	L14				
SMP100LC-160	L16				
SMP100LC-200	L20				
SMP100LC-230	L23				
SMP100LC-270	L27				
SMP100LC-320	L32				
SMP100LC-360	L36				
SMP100LC-400	L40				

6 Revision history

Table 7. Document revision history

Date	Revision	Changes
09-Nov-2004	9	Absolute ratings values, table 3 on page 2, updated.
07-Dec-2004	10	SMP100LC-320, SMP100LC-360 and SMP100LC-400 addition.
20-Jun-2005	11	Telecom Circuit Protector added in Description .
05-Mar-2007	12	Reformatted to current standards. SMB Package information updated. Standards compliance paragraphs added to Description .
05-Jan-2010	13	Corrected vertical axis labelling in Figure 8 .
09-Feb-2012	14	Added UL statement in Complies with the following standards .

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